Field Effect Transistor

Silicon N Channel MOS Type (t-MOS IV)

High Speed, High Current Switching Applications

Features

- Low Drain-Source ON Resistance
- R_{DS(ON)} = 0.24Ω (Typ.) High Forward Transfer Admittance
 - $|Y_{fs}|$ = 15S (Typ.)
- Low Leakage Current
 - $-I_{DSS} = -100\mu A \text{ (Max.) (V}_{DS} = 500\text{V)}$
- Enhancement-Mode
 - $V_{th} = 2.0 \sim 4.0 \text{V} \text{ (V}_{DS} = -10 \text{V}, \text{ I}_{D} = 1 \text{mA)}$

Absolute Maximum Ratings (Ta = 25C)

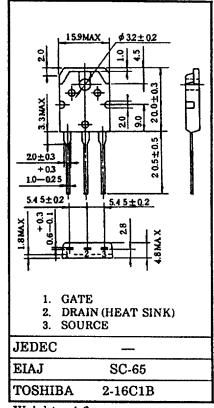
CHARACTERISTI	SYMBOL	RATING	UNIT V		
Drain-Source Voltage		V _{DSS}			500
Drain-Gate Voltage (R _S = 20kΩ)		V _{DGR}	500	٧	
Gate-Source Voltage		V ess	±30	٧	
Drain Current	DC	Ь	20	A	
	Pulse	lop	80		
Drain Power Dissipation (Tc = 25°C)		P _D	150	W	
Channel Temperature		- En	150	°C	
Storage Temperature Range		Itg	-55 - 150	°C	

Thermal Characteristics

CHARACTERISTIC	SYMBOL	MAX.	UNIT	
Thermal Resistance, Channel to Case	D (ch-c)	0.833	°C/W	
Thermal Resistance, Channel to Ambient	fi(ch-a)	50	°C/W	

This transister is an electrostatic sensitive device. Please handle with caution.

Industrial Applications Unit in mm



Weight: 4.6g

Electrical Characteristics (Ta = 25C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		èss	$V_{GS} = \pm 25V$, $V_{DS} = 0V$		-	±10	nA
Gate-Source Breakdown Voltage		V _{(BR) DSS}	$I_{G} = \pm 100V, V_{DS} = 0V$	±30	-	-	μA
Drain Cut-off Current		loss	V _{DS} = 500V, V _{GS} = 0V	-	-	100	μA
Drain-Source Breakdown Voltage		(BR) DSS	I _D = 10mA, V _{GS} = 0V	500	_	-	٧
Gate Threshold Voltage		Y h	V _{DS} = 10V, I _D = -1mA	2.0	-	4.0	٧
Drain-Source ON Resistance		Bs (ON)	V _{GS} = 10V, I _D = 10A	-	0.24	0.30	Ω
Forward Transfer Admittance		Y _{ts} I	V _{DS} = 10V, I _{DS} = 10A	10	15	_	S
Input Capacitance Reverse Transfer Capacitance		Gss	V _{DS} = 10V, V _{GS} = 0V, f = 1MH7	-	3000	4800	ρF
		Çss			220	270	
Output Capacitance		Coss	, ,,,,,,,		830	1200	ρı
Switching Time	Rise Time	tr		_	25	50	
	Turn-on Time	bn	19- O A	_	60	120	ns
	Fall Time	1	Ves ev 100	_	55	110	113
	Turn-off Time	рц	Ves ev	-	280	560	
Total Gate Charge (Gate-Source Plus Gate-Drain) Gate-Source Charge Gate-Drain ("Miller") Charge		O _g	Q _g V _{DD} = 400V, V _{GS} = -10V, ID = -20A	_	65	130	nC
		Q _s		-	40	-	
		Qd		-	25	_	

Source-Drain Diode Ratings and Characteristics (Ta = 25C)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	da	-		_	20	Α
Pulse Drain Reverse Current	DRP	_	-		80	Α
Diode Forward Voltage	Yosf	I _{DR} = 20A, V _{GS} = 0V		-1.0	-1.7	٧
Reverse Recovery Time	*	I _{DR} = 20A, V _{GS} = 0V		450	-	ns
Reverse Recovered Charge	Q,	dl _{DR} / _{dt} = 100A/µs	-	6.8	-	μC

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